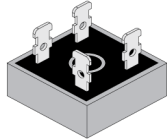


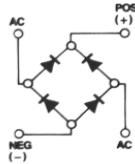
BRIDGE RECTIFIERS

REVERSE VOLTAGE: 50 to 1000 V, FORWARD CURRENT: 25 A

KBPC25XX



KBPC



**KBPC Leaded
Metal Case Package
RoHS compliant**

FEATURE:

1. Electrically Isolated Metal Case for Maximum Heat Dissipation
2. High surge current capability
3. Low power loss, high efficiency
4. Low reverse leakage current
5. Case to terminal isolation voltage 2500V
6. UL Recognized File # E-216968

ABSOLUTE MAXIMUM RATINGS (Ta = 25 °C Unless otherwise specified)

PARAMETER	SYMBOL	KBPC 25005	KBPC 2501	KBPC 2502	KBPC 2504	KBPC 2506	KBPC 2508	KBPC 2510	UNIT
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at $T_c=55^\circ\text{C}$	$I_{(AV)}$	25							A
Peak Forward Surge Current, 8.3ms single half-sine-wave superimposed on rated load (JEDEC method)	I_{FSM}	300							A
Maximum Forward Voltage at 12.5A DC and 25°C	V_F	1.1							V
Maximum Reverse Current at Rated DC Blocking Voltage	I_R	$T_A=25^\circ\text{C}$	10						μA
		$T_A=125^\circ\text{C}$	1000						
Typical Junction Capacitance ¹	C_J	300							pF
Typical Thermal Resistance ²	$R_{\theta JC}$	1.9							$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{stg}	-55 to +150							$^\circ\text{C}$

Notes:

1. Measured at 1MHZ and applied reverse voltage of 4.0 VDC
2. Thermal Resistance from junction to case per leg.

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TYPICAL CHARACTERISTICS CURVES

Fig 1: Forward Current Derating Curve

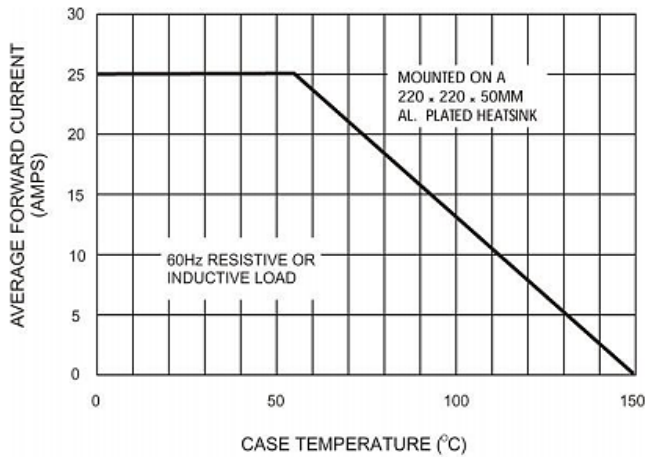


Fig 2: Maximum Non-Repetitive Peak Forward Surge Current Per Bridge Element

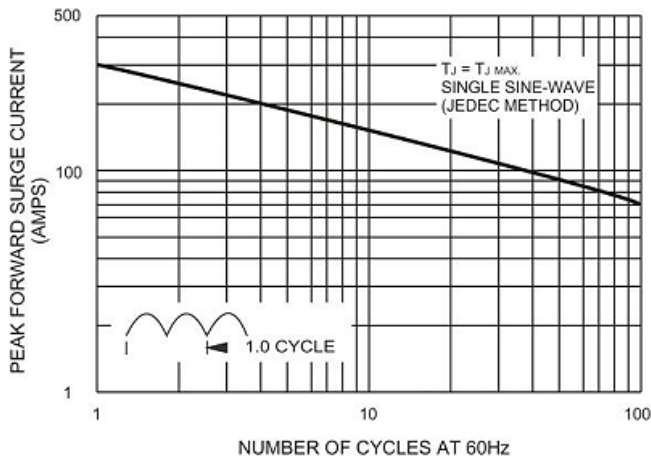


Fig 3: Typical Junction Capacitance Per Bridge Element

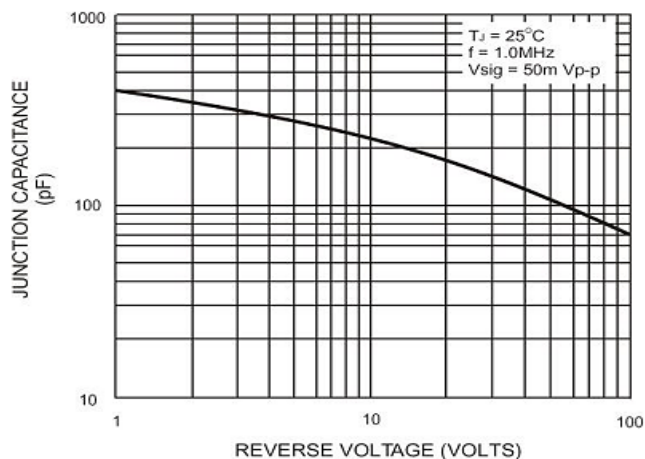


Fig 4: Typical Instantaneous Forward Characteristics Per Bridge Element

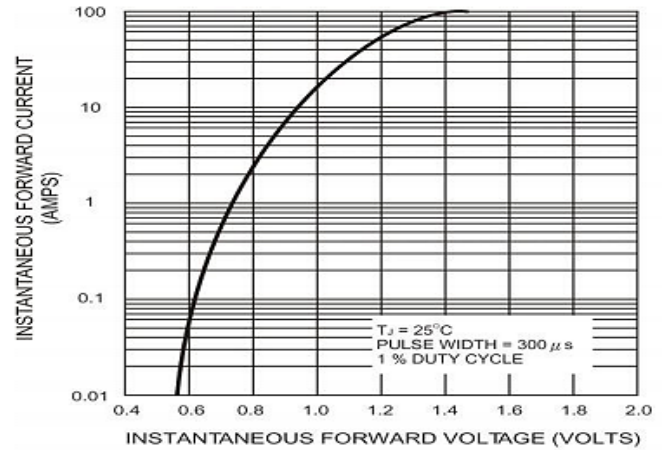


Fig 5: Typical Reverse Leakage Characteristics Per Bridge Element

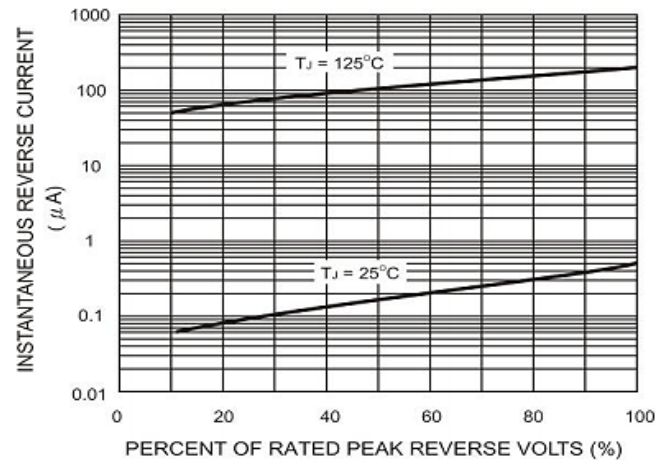
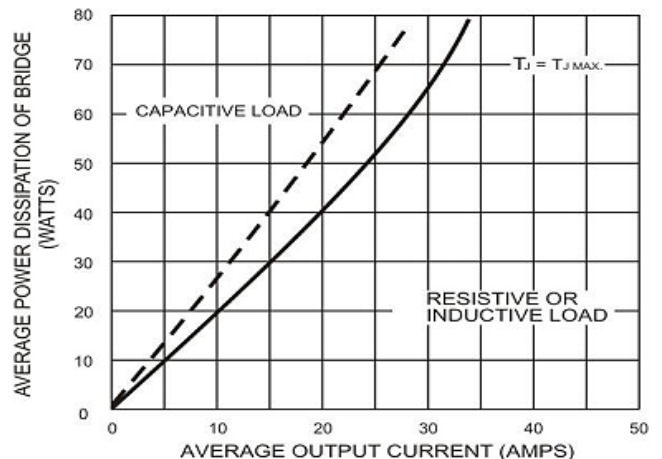
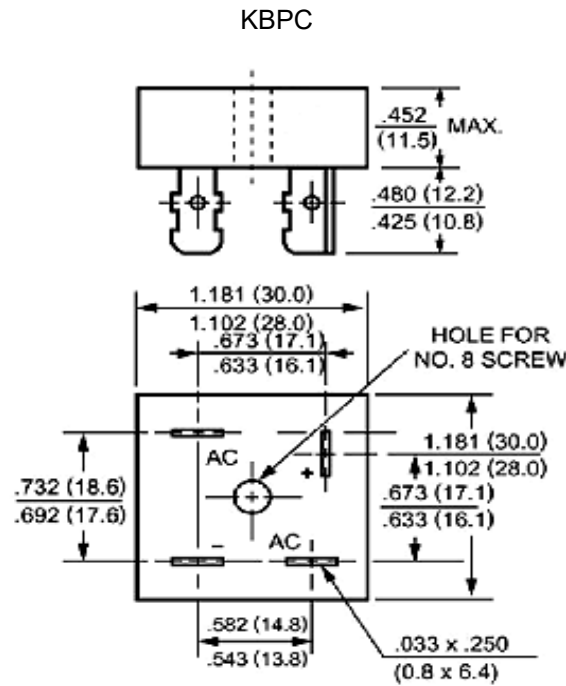


Fig 6: Maximum Power Dissipation



Package Details



Dimensions in inches and (millimeters)

MECHANICAL DATA

Case: Metal or molded plastic with heatsink integrally mounted in the bridge encapsulation

Terminals: Either plated 0.25" (6.35mm) Fasten lugs or plated copper leads 0.040" (1.02mm) diameter.

Mounting position: Thru hole for #8 screw mounting

Weight: 30 gram approx.

Recommended Reflow Solder Profiles

The recommended reflow solder profiles for Pb and Pb-free devices are shown below.

Figure 1 shows the recommended solder profile for devices that have Pb-free terminal plating, and where a Pb-free solder is used.

Figure 2 shows the recommended solder profile for devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with a leaded solder.

Figure 1

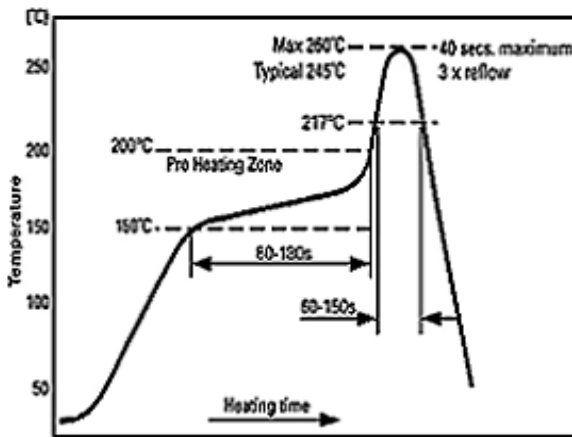
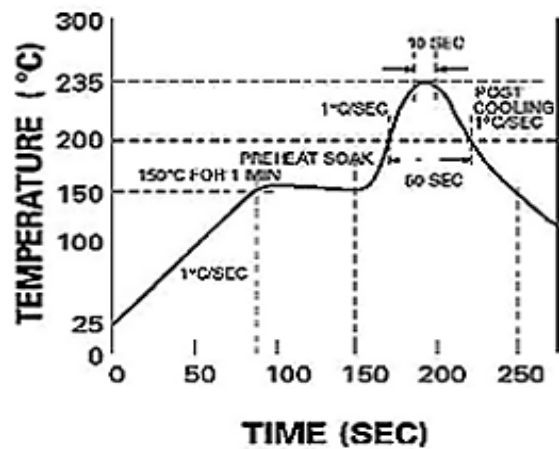


Figure 2



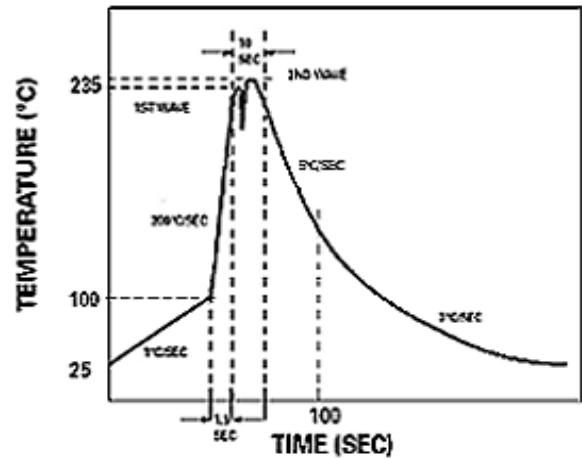
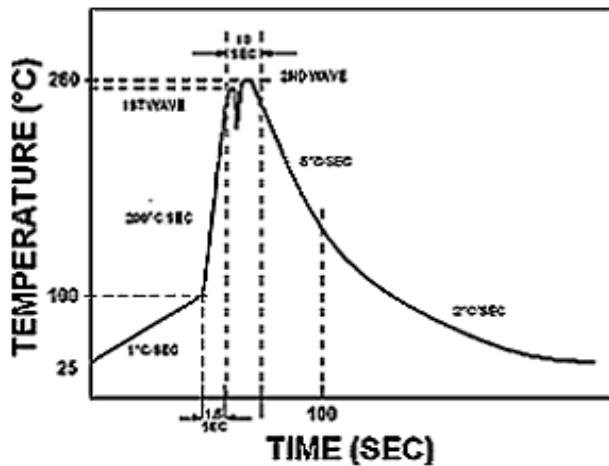
Reflow profiles in tabular form

Profile Feature	Sn-Pb System	Pb-Free System
Average Ramp-Up Rate	~3°C/second	~3°C/second
Preheat		
Time maintained above:		
Peak Temperature	235°C	260°C max.
Time within +0 -5°C of	10 seconds	40 seconds
Ramp-Down Rate	3°C/second max.	6°C/second max

Recommended Wave Solder Profiles

The Recommended solder Profile For Devices with Pb-free terminal plating where a Pb-free solder is used

The Recommended solder Profile For Devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with leaded solder



Wave Profiles in Tabular Form

Profile Feature	Sn-Pb System	Pb-free System
Average Ramp-Up Rate	~200°C/second	~200°C/second
Heating rate during	Typical 1-2, Max 4°C/sec	Typical 1-2, Max 4°C/Sec
Final preheat Temperature	Within 125°C of Solder Temp	Within 125°C of Solder Temp
Peak Temperature	235°C	260°C max.
Time within +0 -5°C of	10 seconds	10 seconds
Ramp-Down Rate	5°C/second max.	5°C/second max.



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Recommended Product Storage Environment for Discrete Semiconductor Devices

This storage environment assumes that the Diodes and transistors are packed properly inside the original packing supplied by CDIL.

- Temperature 5 °C to 30 °C
- Humidity between 40 to 70 %RH
- Air should be clean.
- Avoid harmful gas or dust.
- Avoid outdoor exposure or storage in areas subject to rain or water spraying .
- Avoid storage in areas subject to corrosive gas or dust. Product shall not be stored in areas exposed to direct sunlight.
- Avoid rapid change of temperature.
- Avoid condensation.
- Mechanical stress such as vibration and impact shall be avoided.
- The product shall not be placed directly on the floor.
- The product shall be stored on a plane area. They should not be turned upside down. They should not be placed against the wall.

Shelf Life of CDIL Products

The shelf life of products is the period from product manufacture to shipment to customers. The product can be unconditionally shipped within this period. The period is defined as 2 years.

If products are stored longer than the shelf life of 2 years the products shall be subjected to quality check as per CDIL quality procedure.

The products are further warranted for another one year after the date of shipment subject to the above conditions in CDIL original packing.

Floor Life of CDIL Products and MSL Level

When the products are opened from the original packing, the floor life will start.

For this, the following JEDEC table may be referred:

JEDEC MSL Level		
Level	Time	Condition
1	Unlimited	≤30 °C / 85% RH
2	1 Year	≤30 °C / 60% RH
2a	4 Weeks	≤30 °C / 60% RH
3	168 Hours	≤30 °C / 60% RH
4	72 Hours	≤30 °C / 60% RH
5	48 Hours	≤30 °C / 60% RH
5a	24 Hours	≤30 °C / 60% RH
6	Time on Label(TOL)	≤30 °C / 60% RH

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Customer Notes

Component Disposal Instructions

1. CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD are believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s). CDIL strives for continuous improvement and reserves the right to change the specifications of its products without prior notice.



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